



Material Content Data Sheet



Sales Product Name		BSS223PW H6327		Issued		24. January 2018			
MA#		MA001625110							
Package		PG-SOT323-3-2		Weight*		6.16 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.001	0.02		202		
	noble metal	gold	7440-57-5	0.005	0.08		781		
	inorganic material	silicon	7440-21-3	0.055	0.89	0.99	8856	9839	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		86		
	non noble metal	titanium	7440-32-6	0.003	0.04		432		
	non noble metal	chromium	7440-47-3	0.008	0.13		1295		
	non noble metal	copper	7440-50-8	2.647	42.99	43.17	429969	431782	
wire	non noble metal	copper	7440-50-8	0.005	0.08	0.08	803	803	
encapsulation	organic material	carbon black	1333-86-4	0.031	0.50		5008		
	plastics	epoxy resin	-	0.663	10.77		107666		
	inorganic material	silicondioxide	60676-86-0	2.389	38.81	50.08	388100	500774	
leadfinish	non noble metal	tin	7440-31-5	0.133	2.16	2.16	21554	21554	
plating	noble metal	silver	7440-22-4	0.217	3.52	3.52	35248	35248	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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